

/ Descriptions

TO-92LM PNP Silicon PNP transistor in a TO-92LM Plastic Package.

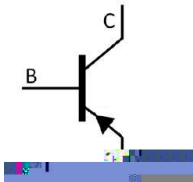
/ Features

2SC2235
Complementary pair with 2SC2235.

/ Applications

Power amplifier applications, driver stage amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	O	Y
h_{FE} Range	80~160	120~240

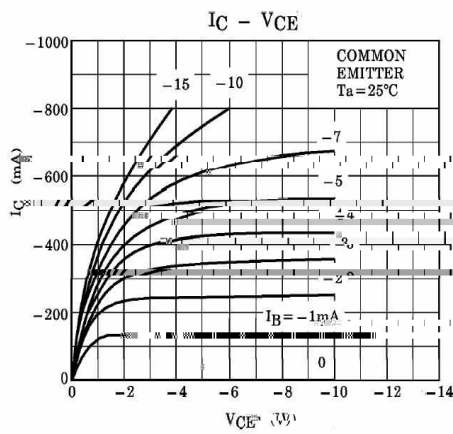
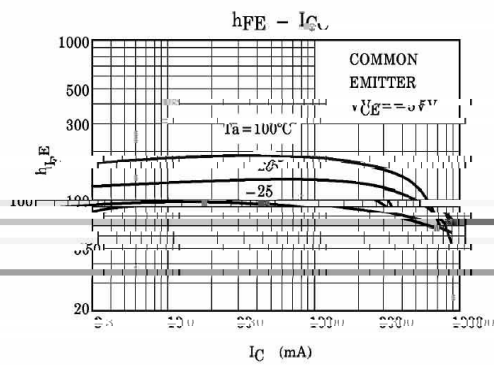
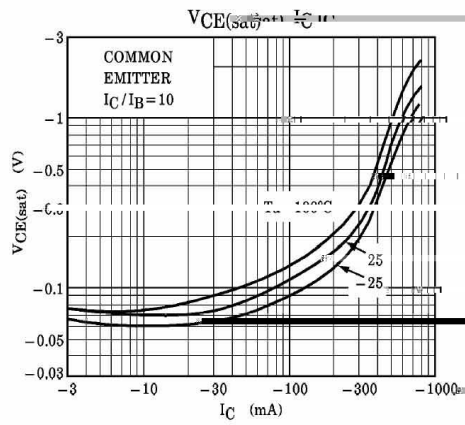
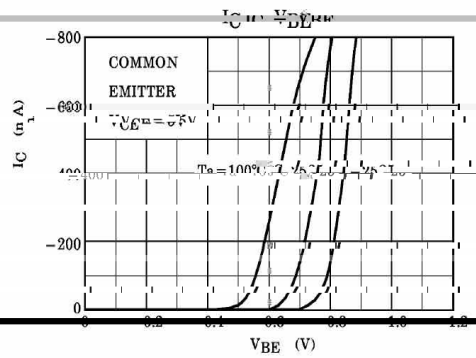
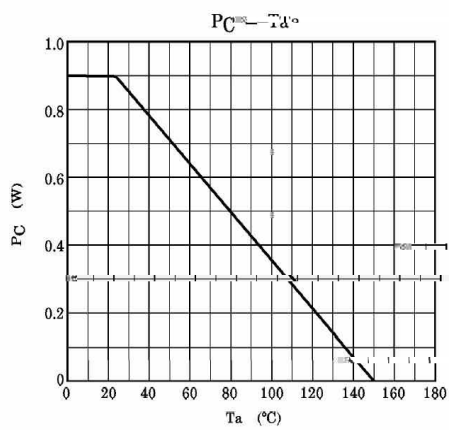
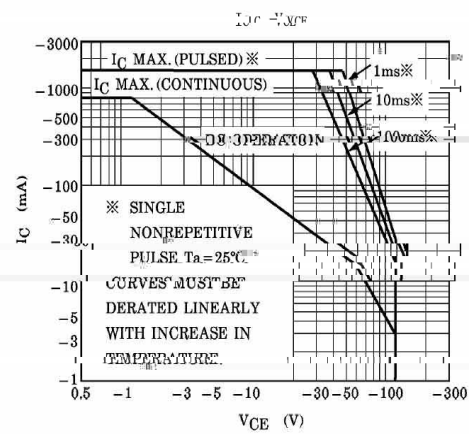
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-120	V
Collector to Emitter Voltage	V_{CEO}	-120	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-800	mA
Emitter Current - Continuous	I_E	800	mA
Collector Power Dissipation	P_C	900	mW
Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C = -10mA$ $I_B = 0$	-120			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E = -1.0mA$ $I_C = 0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = -120V$ $I_E = 0$			-0.1	A
Emitter Cut-Off Current	I_{EBO}	$V_{EB} = -5.0V$ $I_C = 0$			-0.1	A
DC Current Gain	h_{FE}	$V_{CE} = -5.0V$ $I_C = -100mA$	80		240	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -500mA$ $I_B = -50mA$			-1.0	V
Base to Emitter Voltage	V_{BE}	$V_{CE} = -5.0V$ $I_C = -500mA$			-1.0	V
Transition Frequency	f_T	$V_{CE} = -5.0V$ $I_C = -100mA$		120		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -10V$ $I_E = 0$ $f = 1.0MHz$			40	pF

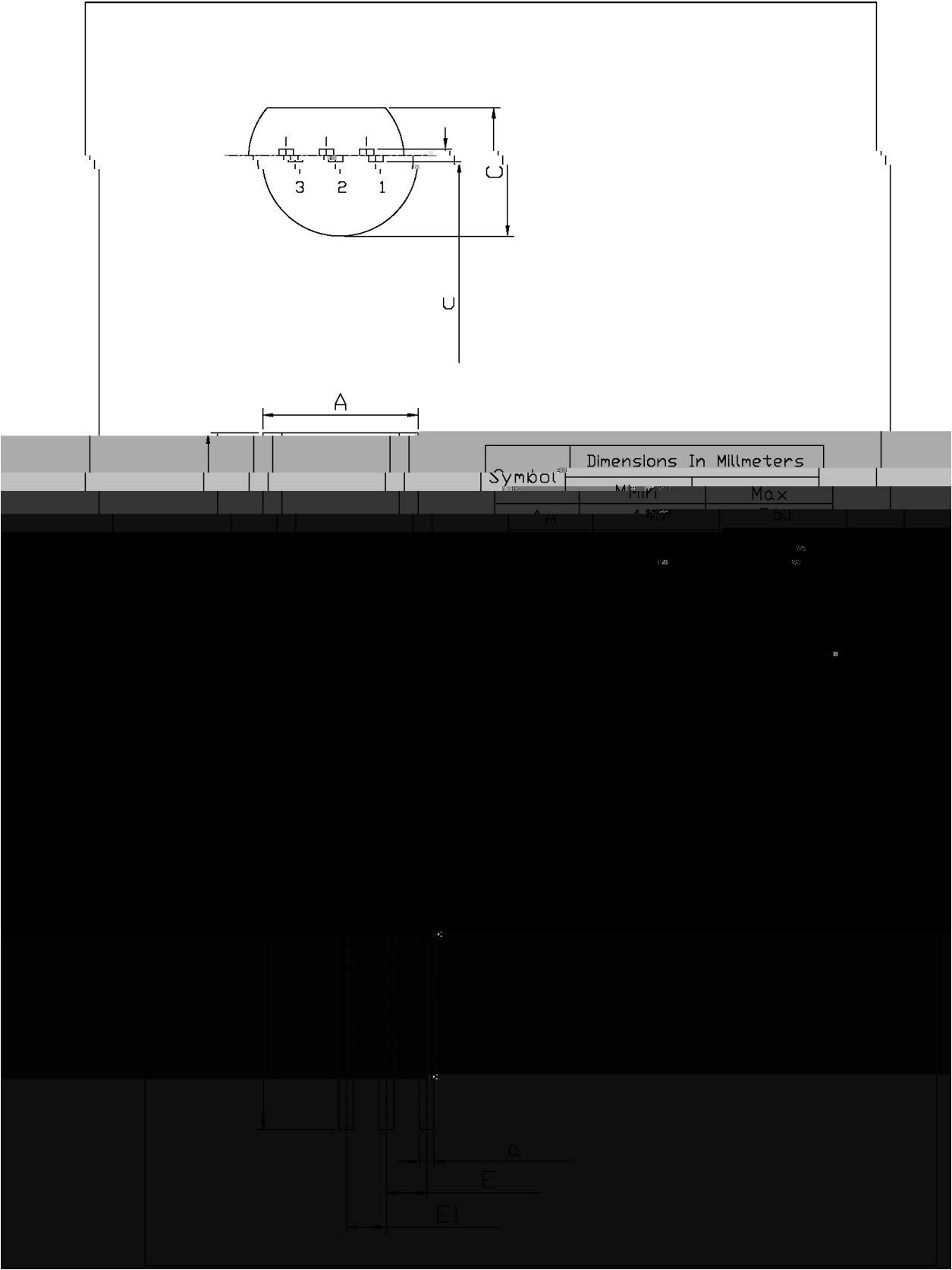
/ Electrical Characteristic Curve



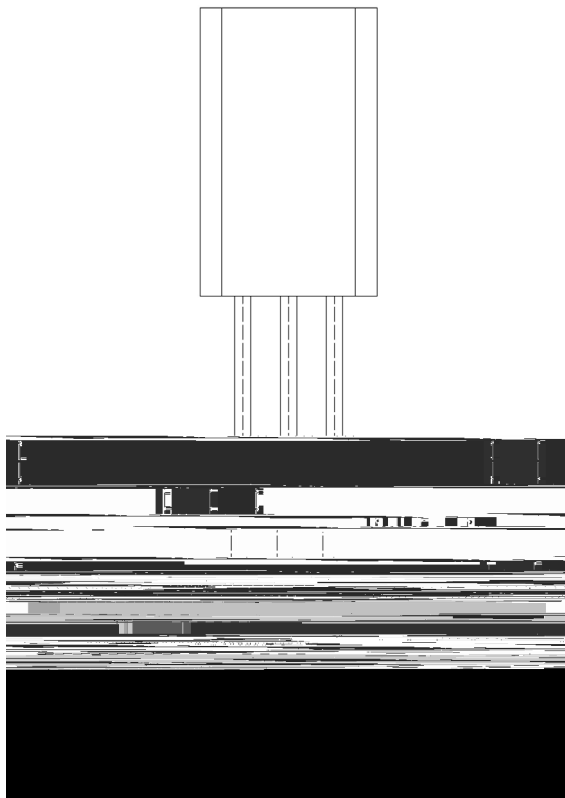
/ Package Dimensions

TO-92LM

Unit: mm



/ Marking Instructions



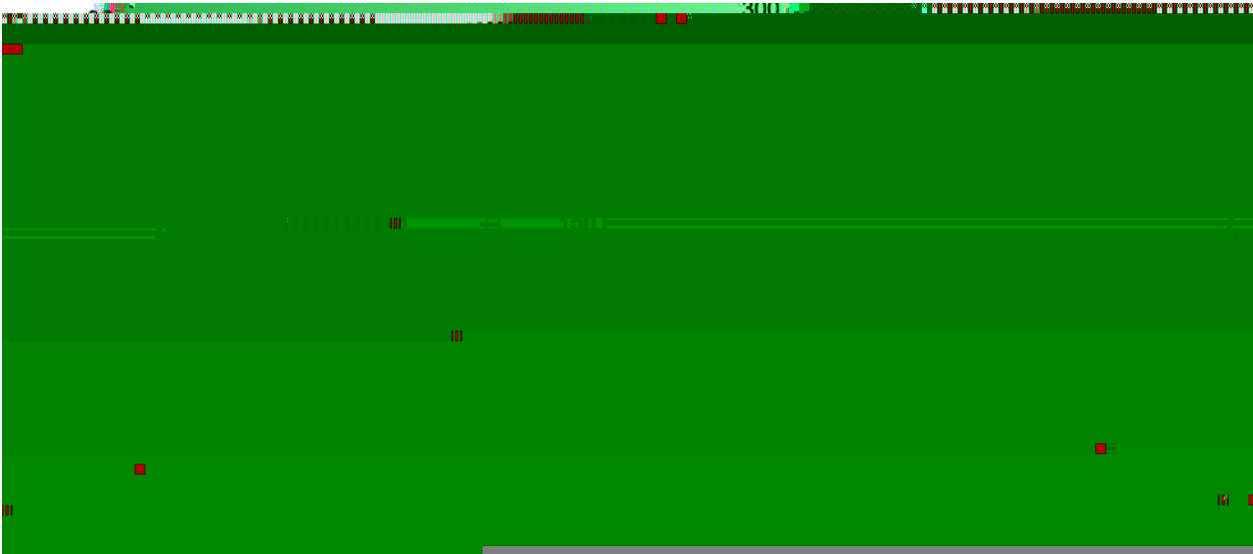
BR:

A965

O: h_{FE}

Note:

() / Temperature Profile for Dip Soldering(Pb-Free)



- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- Note:
1.Preheating:25~150 , Time:60~90sec.
2.Peak Temp.:255±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units	Dimension	(unit mm3)
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